## **WEST Search History**

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DATE: Wednesday, August 03, 2005

Hide?	<u>Set</u> Name	Query	<u>Hit</u> Count			
	DB =	PGPB,USPT,USOC; PLUR=YES; OP=ADJ				
	L38	136 and (wash\$3 or rins\$3)	15			
	DB=	EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ				
	L37	(((semiconductor or wafer or substrate) with polish\$3) same alcohol) and (ethylene oxide)	4			
	DB=	PGPB, USPT, USOC; PLUR=YES; OP=ADJ				
	L36	(((semiconductor or wafer or substrate) with polish\$3) same alcohol) and (ethylene oxide)	49			
	DB=	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD; PLUR=YES; OP=ADJ				
	L35	(((semiconductor or wafer or substrate) with polish\$3) same alcohol) and (ethylene oxide)	53			
C	L34	(((semiconductor or wafer or substrate) with polish\$3) same alcohol) and (dihydrooxirene or (dimethylene oxide) or epoxyethane or 1,2-epoxyethane or (ethene oxide) or oxacyclopropane or oxane or oxidoethane or amprolene or anproline or oxirane)	4			
	DB=EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ					
n	L33	(semiconductor or wafer or substrate) same polish\$3 same (dihydrooxirene or (dimethylene oxide) or epoxyethane or 1,2-epoxyethane or (ethene oxide) or oxacyclopropane or oxane or oxidoethane or amprolene or anproline or oxirane)	0			
	DB=PGPB, USPT, USOC; PLUR=YES; OP=ADJ					
<b>.</b>	L32	(semiconductor or wafer or substrate) same polish\$3 same (dihydrooxirene or (dimethylene oxide) or epoxyethane or 1,2-epoxyethane or (ethene oxide) or etO or oxacyclopropane or oxane or oxidoethane or amprolene or anproline or oxirane)	18			
ń	L31	L30 same (dihydrooxirene or (dimethylene oxide) or epoxyethane or 1,2-epoxyethane or (ethene oxide) or etO or oxacyclopropane or oxane or oxidoethane or amprolene or anproline or oxirane)	0			
	L30	(semiconductor or wafer or substrate or workpiece) same polish\$3 same alcohol same (rins\$3 or wash\$3)	345			
	L29	L27 and (dihydrooxirene or (dimethylene oxide) or epoxyethane or 1,2-epoxyethane or (ethene oxide) or etO or oxacyclopropane or oxane or oxidoethane or amprolene or anproline or oxirane)	5			
	L28	L27 same (dihydrooxirene or (dimethylene oxide) or epoxyethane or 1,2-epoxyethane or (ethene oxide) or etO or oxacyclopropane or oxane or oxidoethane or amprolene or anproline or oxirane)	0			
	L27	(semiconductor or wafer or substrate or workpiece) same (polish\$3 with steps) same alcohol same (rins\$3 or wash\$3)	54			

$\Box$	L26	L25 and 112	10			
	L25	((semiconductor or wafer or substrate or workpiece) same polish\$3) and (octanol or (octyl alcohol) or 1-Octanol or (Caprylic alcohol) or (Heptyl carbinol) or 1-Hydroxyoctane)				
	DB=PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD; PLUR=YES; OP=ADJ					
	L24	((semiconductor or wafer or substrate or workpiece) same polish\$3 same (rins\$3 or wash\$3)) and (octanol or (octyl alcohol) or 1-Octanol or (Caprylic alcohol) or (Heptyl carbinol) or 1-Hydroxyoctane)				
D	L23	((semiconductor or wafer or substrate or workpiece) with polish\$3 with (rins\$3 or wash\$3)) and (octanol or (octyl alcohol) or 1-Octanol or (Caprylic alcohol) or (Heptyl carbinol) or 1-Hydroxyoctane)				
	L22	((semiconductor or wafer or substrate or workpiece) with polish\$3) and (octanol or (octyl alcohol) or 1-Octanol or (Caprylic alcohol) or (Heptyl carbinol) or 1-Hydroxyoctane)				
	L21	(semiconductor or wafer or substrate or workpiece) same polish\$3 same (octanol or (octyl alcohol) or 1-Octanol or (Caprylic alcohol) or (Heptyl carbinol) or 1-Hydroxyoctane)	7			
	DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI; PLUR=YES; OP=ADJ					
<b>.</b>	L20	((semiconductor or wafer or substrate or workpiece) with polish\$3) same (octanol or (octyl alcohol) or 1-Octanol or (Caprylic alcohol) or (Heptyl carbinol) or 1-Hydroxyoctane)	3			
	L19	(semiconductor or wafer or substrate or workpiece) same polish\$3 same(octanol or (octyl alcohol))	7			
	L18	14 and (polish\$3 same(octanol or (octyl alcohol)))	0			
	DB=PGPB,USPT,USOC; PLUR=YES; OP=ADJ					
	L17	19 and (octanol or (octyl alcohol))	0			
	L16	19 and (octanol or (alkyl alcohol))	1			
	L15	19 same (octanol or (alkyl alcohol))	. 0			
	L14	110 same (octanol or (alkyl alcohol))				
	L13	L12 and 110	24			
	L12	510/175;134/2,6,26;438/690,691,692,693.ccls.	8953			
	DB=EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ					
	L11	(polish\$3 with steps) same surfactant same (rins\$3 or wash\$3)	5			
	DB = 1	PGPB, USPT, USOC; PLUR=YES; OP=ADJ				
		(polish\$3 with steps) same surfactant same (rins\$3 or wash\$3)	83			
		PGPB, USPT, USOC, EPAB, JPAB, DWPI; PLUR=YES; OP=ADJ				
	L9	(polish\$3 with steps) same surfactant same (rins\$3 or wash\$3)	88			
	L8	(polish\$3 with steps with plural\$3) same surfactant same (rins\$3 or wash\$3)	0			
	L7	(				
	L6	4				
	L5	L4 and (polish\$3 with surfactant with rins\$3)	. 0			
	L4	Taiwan semiconductor manufacturing	11290			

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n	L3	L1 and (polish\$3 with surfactant)	4
	L2	L1 and (polish\$3 with surfactant with rins\$3)	0
	Ll	chen-ying-ho\$.in.	74

**END OF SEARCH HISTORY**